

**KIOXIA Corporation**

2-5-1, Kasama, Sakae-ku, Yokohama, 247-8585 Japan  
PHONE: 81-45-890-2538  
Date: February 10, 2021  
Ref. No.: 20MQ-G021-2-1(E)

To: \_\_\_\_\_

## **Amendment of PCN#20MQ-G021-2**

This letter is to notify you that our previous PCN # 20MQ-G021-2, dated November 13, 2020, is modified as described below.

### **1. Modification description**

- We previously notified that Powertech Technology Inc. ("PTI") would be an additional assembly site and BGA package materials, such as die attach film (DAF) and bonding wire including diameter, would be changed at PTI.
- **In this amendment, we would like to notify that solder resist material in BGA package substrate will also be changed.** This change will not affect the quality or reliability of our products.

### **2. Scheduled change**

Start of production at PTI, the additional assembly site, will be re-scheduled to **May 2021**.

### **3. Others**

If you would like to order evaluation samples with this additional information, please inform us.

Please acknowledge the above and send us your notification of acceptance by **April 30, 2021**.

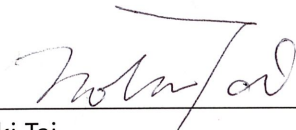
If we do not receive any response by the date above, we will deem this change to be accepted.

If you have any questions on this matter, please contact our sales representatives.

We apologize for any inconvenience this may have caused.

We appreciate your understanding and cooperation.

Sincerely,



Nobuyuki Tai

Group Manager

Memory Customer Quality Engineering Group

Memory Q&R Engineering Department

KIOXIA Corporation